

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| L1 | 3817 | (dcb (direct with (copper u) with (bond bonding bonded))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/10 09:46 |
| L2 | 2 | latent with (heat heated heating) with (storage storing stored) and 1 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/10 09:47 |
| L3 | 2 | (latent with (heat heated heating) with (storage storing stored) and 1 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/10 09:47 |

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|---------|--|---|------------------|---------|------------------|
| L1 | 890 | latent with (heat heated heating) with (storage storing stored) with (module medium device) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/10 07:53 |
| L2 | 6655271 | (die chip ic (integrated adj circuit) semiconductor component) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/10 07:54 |
| L3 | 149 | 1 and 2 and (heat with (sink body dissipate dissipating dissipation dissipated radiate radiation radiated radiating spreader element metal)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/10 07:57 |